Pb Free Plating Product

HFA60PA60CPbF

60Amperes,600Volts Heatsink Common Cathode Ultra Fast Recovery Rectifiers

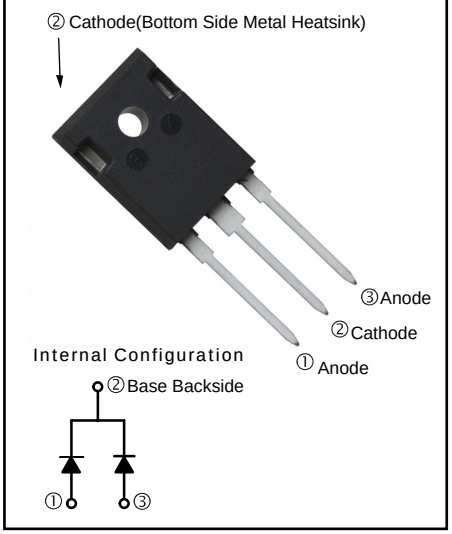
APPLICATION

- Freewheeling, Snubber, Clamp
- Inversion Welder
- PFC
- Plating Power Supply
- Ultrasonic Cleaner and Welder
- Converter & Chopper
- UPS

PRODUCT FEATURE

- Ultrafast Recovery Time
- Soft Recovery Characteristics
- Low Recovery Loss
- Low Forward Voltage
- High Surge Current Capability
- Low Leakage Current

TO-247AD/TO-247-3L(TO-3P)



GENERAL DESCRIPTION

HFA60PA60CPbF using the lastest FRED FAB process(planar passivation chip) with ultrafast and soft recovery characteristic.

Absolute Maximum Ratings

Parameter	Symbol	Test Conditions	Values	Units
Repetitive peak reverse voltage	V_{RRM}		600	V
Continuous forward current	$I_{F(AV)}$	Tc =110°C	60	A
Single pulse forward current	I_{FSM}	Tc =25°C	480	
Maximum repetitive forward current	I_{FRM}	Square wave, 20kHZ	120	
Operating junction	Tj		175	°C
Storage temperatures	Tstg		-55 to +175	°C

Electrical characteristics (Ta=25°C unless otherwise specified)

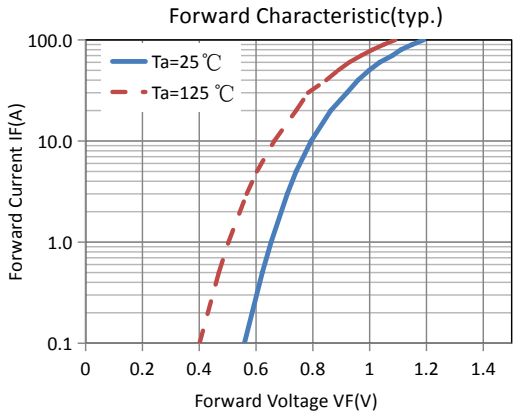
Parameter	Symbol	Test Conditions	Min	Typ.	Max.	Units
Breakdown voltage Blocking voltage	V_{BR}, V_R	I_R=100μA	600			V
Forward voltage (Per Diode)	V_F	I_F=30A		1.30	1.60	
		I_F=30A, Tj =125°C		1.05	1.40	
Reverse leakage current(Per Diode)	I_R	V_R= V_{RRM}			20	μA
		Tj=150°C, V_R=600V			200	
Reverse recovery time(Per Diode)	t_{rr}	I_F=0.5A, I_R=1A, I_{RR}=0.25A		35	45	ns
		I_F=1A,V_R=30V, di/*dt* =200A/us		28	35	

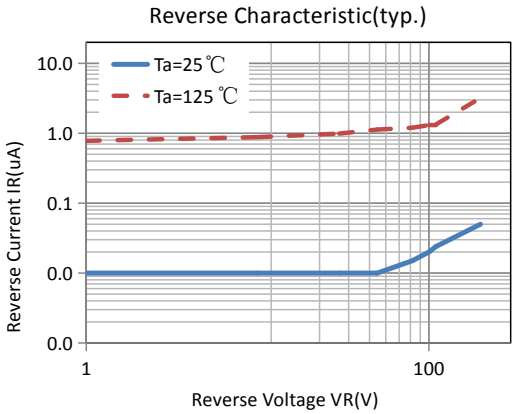
Thermal characteristics

Paramter	Symbol	Typ	Units
Junction-to-Case	$R_{\theta JC}$	0.8	℃/W

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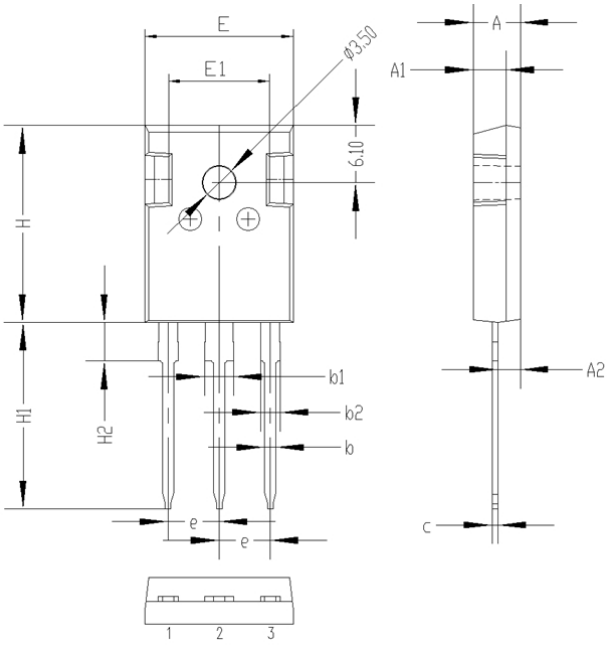
Electrical performance (typical)





Package Information

TO-247 PACKAGE



Symbol	Dimensions(millimeters)	
	Min.	Max.
A	4.80	5.20
A1	3.30	3.70
A2	2.10	2.50
b	1.00	1.40
b1	2.90	3.30
b2	1.90	2.30
c	0.40	0.80
e	5.25	5.65
E	15.6	16.0
E1	10.6	11.00
H	20.8	21.2
H1	19.4	20.4
H2	3.90	4.30
G	5.90	6.30
ΦP	3.30	3.70

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